

FEATURES

- Control Inputs V_{IH}/V_{IL} Levels Are Referenced to V_{CCA} Voltage
- V_{CC} Isolation Feature If Either V_{CC} Input Is at GND, Both Ports Are in the High-Impedance State
- Overvoltage-Tolerant Inputs/Outputs Allow Mixed-Voltage-Mode Data Communications
- Fully Configurable Dual-Rail Design Allows Each Port to Operate Over the Full 1.2-V to 3.6-V Power-Supply Range
- I_{off} Supports Partial-Power-Down Mode Operation
- I/Os Are 4.6-V Tolerant
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 8000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

DESCRIPTION/ORDERING INFORMATION

This 16-bit noninverting bus transceiver uses two separate configurable power-supply rails. The SN74AVC16T245 is optimized to operate with V_{CCA}/V_{CCB} set at 1.4 V to 3.6 V. It is operational with V_{CCA}/V_{CCB} as low as 1.2 V. The A port is designed to track V_{CCA} . V_{CCA} accepts any supply voltage from 1.2 V to 3.6 V. The B port is designed to track V_{CCB} . V_{CCB} accepts any supply voltage from 1.2 V to 3.6 V. The B port is designed to track V_{CCB} . V_{CCB} accepts any supply voltage from 1.2 V to 3.6 V. This allows for universal low-voltage bidirectional translation between any of the 1.2-V, 1.5-V, 1.8-V, 2.5-V, and 3.3-V voltage nodes.

	(TOP V	'IEW)
1DIR [1	48 1 0E
1B1 [2	47 1A1
1B2 [3	46 1A2
GND [4	45 GND
1B3]	5	44 1A3
1В4 [6	43 1A4
V _{ССВ} [7	42 V _{CCA}
1B5 [8	41 1A5
1B6 [9	40 1A6
GND [10	39 GND
1B7 [11	38 1A7
1B8 [12	37 1A8
2B1 [13	36 2A1
2B2 [14	35 2A2
GND	15	34 GND
2B3 [16	33 2A3
2B4 [17	32 2A4
V _{CCB}	18 19	31 V _{CCA} 30 2A5
2B6	20	29 2A6
GND [21	28 GND
2B7 [22	27 2A7
2B8 [23	26 2A8
2DIR [24	25 2 0E

SCES551C-FEBRUARY 2004-REVISED AUGUST 2005

DGG OR DGV PACKAGE

The SN74AVC16T245 is designed for asynchronous communication between data buses. The device transmits data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the outputs so the buses effectively are isolated.

The SN74AVC16T245 is designed so that the control pins (1DIR, 2DIR, 1OE, and 2OE) are supplied by V_{CCA}.

T _A	PACKAGE	(1)	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	TSSOP – DGG	Tape and reel	SN74AVC16T245DGGR	AVC16T245	
4000 to 0500	TVSOP – DGV	Tape and reel	SN74AVC16T245DGVR	WF245	
–40°C to 85°C	VFBGA – GQL	Topo and roal	SN74AVC16T245GQLR	WF245	
	VFBGA – ZQL (Pb-free)	Tape and reel	SN74AVC16T245ZQLR	VVF243	

ORDERING INFORMATION

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



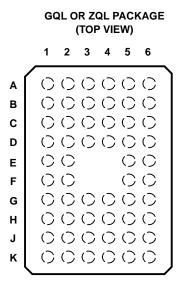
SCES551C-FEBRUARY 2004-REVISED AUGUST 2005

DESCRIPTION/ORDERING INFORMATION (CONTINUED)

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

The V_{CC} isolation feature ensures that if either V_{CC} input is at GND, both ports are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.



TERMINAL ASSIGNMENTS⁽²⁾

	1	2	3	4	5	6
Α	1DIR	NC	NC	NC	NC	1 0E
В	1B2	1B1	GND	GND	1A1	1A2
С	1B4	1B3	V _{CCB}	V _{CCA}	1A3	1A4
D	1B6	1B5	GND	GND	1A5	1A6
E	1B8	1B7			1A7	1A8
F	2B1	2B2			2A2	2A1
G	2B3	2B4	GND	GND	2A4	2A3
н	2B5	2B6	V _{CCB}	V _{CCA}	2A6	2A5
J	2B7	2B8	GND	GND	2A8	2A7
к	2DIR	NC	NC	NC	NC	2 0E

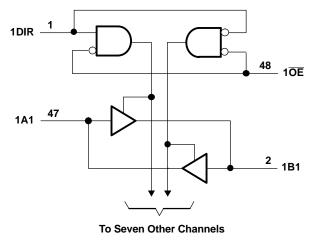
(2) NC - No internal connection

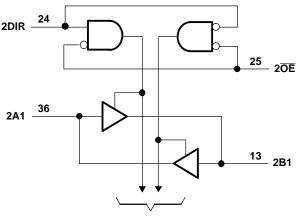
FUNCTION TABLE (EACH 8-BIT SECTION)

INP	UTS	OPERATION
OE	DIR	OFERATION
L	L	B data to A bus
L	н	A data to B bus
н	Х	Isolation

SCES551C-FEBRUARY 2004-REVISED AUGUST 2005

LOGIC DIAGRAM (POSITIVE LOGIC)





To Seven Other Channels

Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
$V_{CCA} V_{CCB}$	Supply voltage range		-0.5	4.6	V
		I/O ports (A port)	-0.5	4.6	
VI	Input voltage range ⁽²⁾	I/O ports (B port)	-0.5	4.6	V
		Control inputs	-0.5	4.6	
v	Voltage range applied to any output	A port	-0.5	4.6	V
Vo	in the high-impedance or power-off state ⁽²⁾	B port	-0.5	4.6	v
v	Voltage reaction (2)	A port	-0.5	V _{CCA} + 0.5	V
Vo	Voltage range applied to any output in the high or low state $^{(2)(3)}$	B port	-0.5	V _{CCB} + 0.5	V
I _{IK}	Input clamp current	V ₁ < 0		-50	mA
I _{OK}	Output clamp current	V _O < 0		-50	mA
I _O	Continuous output current			±50	mA
	Continuous current through each V_{CCA} , V_{CCB} , and GND			±100	mA
		DGG package		70	
θ_{JA}	Package thermal impedance ⁽⁴⁾	DGV package		58	°C/W
		GQL/ZQL package		42	
T _{stg}	Storage temperature range		-65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input voltage and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

(3) The output positive-voltage rating may be exceeded up to 4.6 V maximum if the output current rating is observed.

(4) The package thermal impedance is calculated in accordance with JESD 51-7.

SCES551C-FEBRUARY 2004-REVISED AUGUST 2005



			V _{CCI}	V _{cco}	MIN	MAX	UNIT
V _{CCA}	Supply voltage				1.2	3.6	V
V _{CCB}	Supply voltage				1.2	3.6	V
			1.2 V to 1.95 V		$V_{CCI} imes 0.65$		
V _{IH}	High-level input voltage	Data inputs ⁽⁴⁾	1.95 V to 2.7 V		1.6		V
	input voltage		2.7 V to 3.6 V		2		
			1.2 V to 1.95 V			$V_{CCI} imes 0.35$	
V _{IL}	Low-level input voltage	Data inputs ⁽⁴⁾	1.95 V to 2.7 V			0.7	V
	input voltage		2.7 V to 3.6 V			0.8	
			1.2 V to 1.95 V		$V_{CCA} \times 0.65$		
V _{IH}	High-level input voltage	DIR (referenced to V _{CCA}) ⁽⁵⁾	1.95 V to 2.7 V		1.6		V
	input voltage		2.7 V to 3.6 V		2		
			1.2 V to 1.95 V			$V_{CCA}\ \times 0.35$	
V _{IL}	input voltage	DIR (referenced to V _{CCA}) ⁽⁵⁾	1.95 V to 2.7 V			0.7	V
		(referenced to v _{CCA}).	2.7 V to 3.6 V			0.8	
VI	Input voltage				0	3.6	V
<i></i>	Output voltogo	Active state			0	V _{CCO}	V
Vo	Output voltage	3-state			0	3.6	v
				1.2 V		-3	
				1.4 V to 1.6 V		-6	
l _{он}	High-level output cu	irrent		1.65 V to 1.95 V		-8	mA
				2.3 V to 2.7 V		-9	
				3 V to 3.6 V		-12	
				1.2 V		3	
				1.4 V to 1.6 V		6	
OL	Low-level output cu	rrent		1.65 V to 1.95 V		8	mA
				2.3 V to 2.7 V		9	
				3 V to 3.6 V		12	
Δt/Δv	Input transition rise	or fall rate				ns/V	
T _A	Operating free-air te	emperature			-40	85	°C

V_{CCI} is the V_{CC} associated with the data input port.
 V_{CCO} is the V_{CC} associated with the output port.
 All unused data inputs of the device must be held at V_{CCI} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.
 For V_{CCI} values not specified in the data sheet, V_{IH} min = V_{CCI} × 0.7 V, V_{IL} max = V_{CCI} × 0.3 V.
 For V_{CCA} values not specified in the data sheet, V_{IH} min = V_{CCA} × 0.7 V, V_{IL} max = V_{CCA} × 0.3 V.

SCES551C-FEBRUARY 2004-REVISED AUGUST 2005

Ĵ. Texas INSTRUMENTS www.ti.com

Electrical Characteristics⁽¹⁾⁽²⁾

over recommended operating free-air temperature range (unless otherwise noted)

	METER	TEST COND	TIONS	v	v	т,	_A = 25°C		–40°C to 8	5°C	UNIT	
PAR	AWEIER	TEST COND	TIONS	V _{CCA}	V _{CCB}	MIN	TYP	MAX	MIN	MAX	UNI	
		I _{OH} = -100 μA		1.2 V to 3.6 V	1.2 V to 3.6 V				V _{CCO} – 0.2			
		$I_{OH} = -3 \text{ mA}$		1.2 V	1.2 V		0.95					
		I _{OH} = -6 mA		1.4 V	1.4 V				1.05			
V _{OH}		I _{OH} = -8 mA	$V_{I} = V_{IH}$	1.65 V	1.65 V				1.2		V	
		I _{OH} = -9 mA		2.3 V	2.3 V				1.75			
		I _{OH} = -12 mA		3 V	3 V				2.3			
		I _{OL} = 100 μA		1.2 V to 3.6 V	1.2 V to 3.6 V					0.2		
		I _{OL} = 3 mA		1.2 V	1.2 V		0.15					
.,		I _{OL} = 6 mA	$V_{I} = V_{IL}$	1.4 V	1.4 V					0.35	V	
V _{OL}	$I_{OL} = 8 \text{ mA}$ $I_{OL} = 9 \text{ mA}$		$v_{I} = v_{IL}$	1.65 V	1.65 V					0.45	v	
				2.3 V	2.3 V					0.55		
		I _{OL} = 12 mA		3 V	3 V					0.7		
I	Control inputs	$V_{I} = V_{CCA} \text{ or } GND$		1.2 V to 3.6 V	1.2 V to 3.6 V		±0.025	±0.25		±1	μA	
	A or B port	V		0 V	0 to 3.6 V		±0.1	±2.5		±5		
I _{off}	A or B port	$V_1 \text{ or } V_0 = 0 \text{ to } 3$	3.6 V	0 to 3.6 V	0 V		±0.5	±2.5		±5	μA	
I _{OZ} ⁽³⁾	A or B port	$V_0 = V_{CC0}$ or G $V_I = V_{CCI}$ or GN $\overline{OE} = V_{IH}$	ND, D,	3.6 V	3.6 V		±0.5	±2.5		±5	μA	
			_	1.2 V to 3.6 V	1.2 V to 3.6 V					25		
I _{CCA}		$V_{I} = V_{CCI}$ or GN $I_{O} = 0$	D,	0 V	3.6 V					-5	μA	
		0 - 0		3.6 V	0 V					25		
				1.2 V to 3.6 V	1.2 V to 3.6 V					25		
I _{CCB}		$V_{I} = V_{CCI}$ or GN $I_{O} = 0$	D,	0 V	3.6 V					25	μA	
		0-0		3.6 V	0 V					-5		
I _{CCA} +	I _{CCB}	$V_{I} = V_{CCI}$ or GN $I_{O} = 0$	D,	1.2 V to 3.6 V	1.2 V to 3.6 V					45	μA	
C _i	Control inputs	V _I = 3.3 V or GN	ND	3.3 V	3.3 V		3.5				pF	
C _{io}	A or B port	$V_{O} = 3.3 \text{ V or G}$	ND	3.3 V	3.3 V		7				pF	

V_{CCO} is the V_{CC} associated with the output port.
 V_{CCI} is the V_{CC} associated with the input port.
 For I/O ports, the parameter I_{OZ} includes the input leakage current.



SCES551C-FEBRUARY 2004-REVISED AUGUST 2005

Switching Characteristics

over recommended operating free-air temperature range, $V_{CCA} = 1.2 \text{ V}$ (see Figure 11)

	FROM	то	V _{CCB} = 1.2 V	V _{CCB} = 1.5 V	V _{CCB} = 1.8 V	V _{CCB} = 2.5 V	V _{CCB} = 3.3 V	
PARAMETER	(INPUT)	(OUTPUT)	ТҮР	ТҮР	ТҮР	ТҮР	ТҮР	UNIT
t _{PLH}	А	В	4.1	3.3	3	2.8	3.2	5
t _{PHL}	A	Б	4.1	3.3	3	2.8	3.2	ns
t _{PLH}	В	А	4.4	4	3.8	3.6	3.5	5
t _{PHL}	D	A	4.4	4	3.8	3.6	3.5	ns
t _{PZH}	OE	А	6.4	6.4	6.4	6.4	6.4	2
t _{PZL}	UE	A	6.4	6.4	6.4	6.4	6.4	ns
t _{PZH}	OE	В	6	4.6	4	3.4	3.2	20
t _{PZL}	UE	Б	6	4.6	4	3.4	3.2	ns
t _{PHZ}	OE	•	6.6	6.6	6.6	6.6	6.8	5
t _{PLZ}	UE	A	6.6	6.6	6.6	6.6	6.8	ns
t _{PHZ}	ŌĒ	Р	6	4.9	4.9	4.2	5.3	20
t _{PLZ}	UE	В	6	4.9	4.9	4.2	5.3	ns

Switching Characteristics

over recommended operating free-air temperature range, V_{CCA} = 1.5 V \pm 0.1 V (see Figure 11)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CCB} = 1.2 V	V _{ССВ} = ± 0.1		V _{ССВ} = ± 0.1		V _{ССВ} = ± 0.2		V _{ССВ} = ± 0.3		UNIT	
	(INFUT)	(001201)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
t _{PLH}	А	В	3.6	0.5	6.2	0.5	5.2	0.5	4.1	0.5	3.7	20	
t _{PHL}	A	Б	3.6	0.5	6.2	0.5	5.2	0.5	4.1	0.5	3.7	ns	
t _{PLH}	В	А	3.3	0.5	6.2	0.5	5.9	0.5	5.6	0.5	5.5	20	
t _{PHL}	D	В	A	3.3	0.5	6.2	0.5	5.9	0.5	5.6	0.5	5.5	ns
t _{PZH}	ŌĒ	А	4.3	1	10.1	1	10.1	1	10.1	1	10.1	20	
t _{PZL}		ÛE	A	4.3	1	10.1	1	10.1	1	10.1	1	10.1	ns
t _{PZH}	ŌĒ	В	5.6	1	10.1	0.5	8.1	0.5	5.9	0.5	5.2	20	
t _{PZL}	UE	Б	5.6	1	10.1	0.5	8.1	0.5	5.9	0.5	5.2	ns	
t _{PHZ}		^	4.5	1.5	9.1	1.5	9.1	1.5	9.1	1.5	9.1	20	
t _{PLZ}	OE	A	4.5	1.5	9.1	1.5	9.1	1.5	9.1	1.5	9.1	ns	
t _{PHZ}	ŌĒ	ŌĒ	Р	5.5	1.5	8.7	1.5	7.5	1	6.5	1	6.3	20
t _{PLZ}			ŌĒ	В	5.5	1.5	8.7	1.5	7.5	1	6.5	1	6.3

SCES551C-FEBRUARY 2004-REVISED AUGUST 2005

Switching Characteristics

Texas

INSTRUMENTS www.ti.com

Ĵ.

over recommended operating free-air temperature range, $V_{CCA} = 1.8 \text{ V} \pm 0.15 \text{ V}$ (see Figure 11)

PARAMETER	FROM	TO	$V_{CCB} = 1.2 V \qquad \begin{array}{c} V_{CCB} = 1.5 V \\ \pm 0.1 V \end{array} \qquad \begin{array}{c} V_{CCB} = 1.8 V \\ \pm 0.15 V \end{array}$		V_{CCB} = 2.5 V ± 0.2 V		V _{ССВ} = ± 0.3		UNIT				
	(INPUT)	(OUTPUT)	ТҮР	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
t _{PLH}	٨	В	3.4	0.5	5.9	0.5	4.8	0.5	3.7	0.5	3.3		
t _{PHL}	A	В	3.4	0.5	5.9	0.5	4.8	0.5	3.7	0.5	3.3	ns	
t _{PLH}	В	А	3	0.5	5.2	0.5	4.8	0.5	4.5	0.5	4.4		
t _{PHL}	Б	A	3	0.5	5.2	0.5	4.8	0.5	4.5	0.5	4.4	ns	
t _{PZH}	ŌĒ	А	3.4	1	7.8	1	7.8	1	7.8	1	7.8		
t _{PZL}			3.4	1	7.8	1	7.8	1	7.8	1	7.8	ns	
t _{PZH}	OE	В	5.4	1	9.2	0.5	7.4	0.5	5.3	0.5	4.5		
t _{PZL}	UE	В	5.4	1	9.2	0.5	7.4	0.5	5.3	0.5	4.5	ns	
t _{PHZ}		٨	4.2	1.5	7.7	1.5	7.7	1.5	7.7	1.5	7.7	20	
t _{PLZ}	ŌĒ	OE A	4.2	1.5	7.7	1.5	7.7	1.5	7.7	1.5	7.7	ns	
t _{PHZ}	ŌE	ŌĒ	В	5.2	1.5	8.4	1.5	7.1	1	5.9	1	5.7	20
t _{PLZ}			в	5.2	1.5	8.4	1.5	7.1	1	5.9	1	5.7	ns

Switching Characteristics

over recommended operating free-air temperature range, V_{CCA} = 2.5 V \pm 0.2 V (see Figure 11)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CCB} = 1.2 V	V _{CCB} = ± 0.1	1.5 V 1 V	V _{ССВ} = ± 0.1		V _{ССВ} = ± 0.2		V _{ССВ} = ± 0.3		UNIT								
	(INFUT)	(001201)	ТҮР	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX									
t _{PLH}	А	В	3.2	0.5	5.6	0.5	4.5	0.5	3.3	0.5	2.8	~~								
t _{PHL}	A	Б	3.2	0.5	5.6	0.5	4.5	0.5	3.3	0.5	2.8	ns								
t _{PLH}	В	А	2.6	0.5	4.1	0.5	3.7	0.5	3.3	0.5	3.2	20								
t _{PHL}	D	D	A	2.6	0.5	4.1	0.5	3.7	0.5	3.3	0.5	3.2	ns							
t _{PZH}		А	2.5	0.5	5.3	0.5	5.3	0.5	5.3	0.5	5.3	~~								
t _{PZL}	ŌĒ	OE	UE	A	2.5	0.5	5.3	0.5	5.3	0.5	5.3	0.5	5.3	ns						
t _{PZH}	ŌĒ	В	5.2	0.5	9.4	0.5	7.3	0.5	5.1	0.5	4.5	~~~								
t _{PZL}	UE	Б	5.2	0.5	9.4	0.5	7.3	0.5	5.1	0.5	4.5	ns								
t _{PHZ}		А	3	1	6.1	1	6.1	1	6.1	1	6.1	20								
t _{PLZ}	OE	A	3	1	6.1	1	6.1	1	6.1	1	6.1	ns								
t _{PHZ}	ŌĒ	ŌĒ	P	5	1	7.9	1	6.6	1	6.1	1	5.2	20							
t _{PLZ}			ŌĒ	ŌĒ	OE	ŌĒ	OE	ŌĒ	ŌĒ	ŌĒ	OE	OE B	5	1	7.9	1	6.6	1	6.1	1



SCES551C-FEBRUARY 2004-REVISED AUGUST 2005

Switching Characteristics

over recommended operating free-air temperature range, V_{CCA} = 3.3 V \pm 0.3 V (see Figure 11)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CCB} = 1.2 V	V _{ССВ} = ± 0.1		V _{CCB} = ± 0.1		V _{CCB} = ± 0.2		V _{ССВ} = ± 0.3		UNIT											
	(INFUT)	(001201)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX												
t _{PLH}	А	В	3.2	0.5	5.5	0.5	4.4	0.5	3.2	0.5	2.7	20											
t _{PHL}	A	Б	3.2	0.5	5.5	0.5	4.4	0.5	3.2	0.5	2.7	ns											
t _{PLH}	В	А	2.8	0.5	3.7	0.5	3.3	0.5	2.8	0.5	2.7	ns											
t _{PHL}	D	D	A	2.8	0.5	3.7	0.5	3.3	0.5	2.8	0.5	2.7	115										
t _{PZH}	ŌĒ	А	2.2	0.5	4.3	0.5	4.2	0.5	4.1	0.5	4	20											
t _{PZL}		OE	A	2.2	0.5	4.3	0.5	4.2	0.5	4.1	0.5	4	ns										
t _{PZH}	ŌĒ	В	5.1	0.5	9.3	0.5	7.2	0.5	4.9	0.5	4	20											
t _{PZL}	0E	Б	5.1	0.5	9.3	0.5	7.2	0.5	4.9	0.5	4	ns											
t _{PHZ}		^	3.4	0.5	5	0.5	5	0.5	5	0.5	5	20											
t _{PLZ}	ŌĒ	ŌĒ	OE	ŌĒ	A	3.4	0.5	5	0.5	5	0.5	5	0.5	5	ns								
t _{PHZ}		Р	4.9	1	7.7	1	6.5	1	5.2	0.5	5	20											
t _{PLZ}	ŌĒ	ŌĒ	ŌĒ	OE	ŌĒ	ŌĒ	ŌĒ	ŌĒ	OE	ŌĒ	ŌĒ	ŌĒ	OE B —	4.9	1	7.7	1	6.5	1	5.2	0.5	5	ns

Operating Characteristics

 $T_A = 25^{\circ}C$

PARAMETER		TEST CONDITIONS	V _{CCA} = V _{CCB} = 1.2 V	V _{CCA} = V _{CCB} = 1.5 V	V _{CCA} = V _{CCB} = 1.8 V	V _{CCA} = V _{CCB} = 2.5 V	V _{CCA} = V _{CCB} = 3.3 V	UNIT		
			••••••	TYP	TYP	TYP	TYP	TYP		
A to E C _{pdA} ⁽¹⁾ B to A	A to B	Outputs enabled		1	1	1	1	2		
	AIUB	Outputs disabled	C _L = 0, f = 10 MHz,	1	1	1	1	1	pF	
	B to A	Outputs enabled	$t_r = t_f = 1 \text{ ns}$	13	13	14	15	16		
		Outputs disabled		1	1	1	1	1		
	A to B	Outputs enabled	C _L = 0, f = 10 MHz, t _r = t _f = 1 ns	13	13	14	15	16		
C _{pdB} ⁽¹⁾	AIUB	Outputs disabled		1	1	1	1	1	pF	
	B to A	Outputs enabled		1	1	1	1	2	μг	
		Outputs disabled		1	1	1	1	1		

(1) Power dissipation capacitance per transceiver

V	V _{CCA}								
V _{CCB}	0 V	1.2 V	1.5 V	1.8 V	2.5 V	3.3 V	UNIT		
0 V	0	<0.5	<0.5	<0.5	<0.5	<0.5			
1.2 V	<0.5	<1	<1	<1	<1	1			
1.5 V	<0.5	<1	<1	<1	<1	1			
1.8 V	<0.5	<1	<1	<1	<1	<1	μΑ		
2.5 V	<0.5	1	<1	<1	<1	<1			
3.3 V	<0.5	1	<1	<1	<1	<1			

Table 1. Typical Total Static Power Consumption (I_{CCA} + I_{CCB})

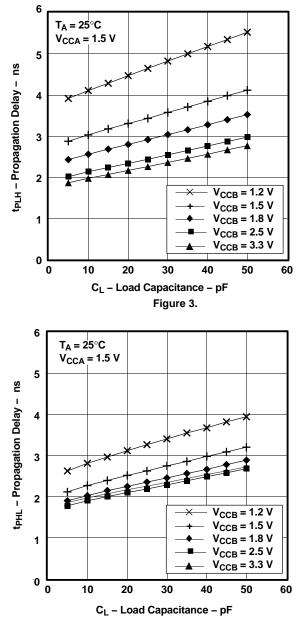
SN74AVC16T245 16-BIT DUAL-SUPPLY BUS TRANSCEIVER WITH CONFIGURABLE VOLTAGE TRANSLATION AND 3-STATE OUTPUTS SCES551C-FEBRUARY 2004-REVISED AUGUST 2005



TYPICAL CHARACTERISTICS 6 T_A = 25°C V_{CCA} = 1.2 V 5 t_{PLH} – Propagation Delay – ns 4 3 Ł F 2 $V_{CCB} = 1.2 V$ $V_{CCB} = 1.5 V$ $V_{CCB} = 1.8 V$ $V_{CCB} = 2.5 V$ 1 $V_{CCB} = 3.3 V$ 0 0 10 20 30 40 50 60 C_L – Load Capacitance – pF Figure 1. 6 T_A = 25°C V_{CCA} = 1.2 V 5 t_{PHL} – Propagation Delay – ns 4 3 2 V_{CCB} = 1.2 V V_{CCB} = 1.5 V V_{CCB} = 1.8 V 1 $V_{CCB} = 2.5 V$ $V_{CCB} = 3.3 V$ 0 ^L 0 10 40 20 30 50 60 C_L – Load Capacitance – pF

Figure 2.

SCES551C-FEBRUARY 2004-REVISED AUGUST 2005



TYPICAL CHARACTERISTICS

-Ü

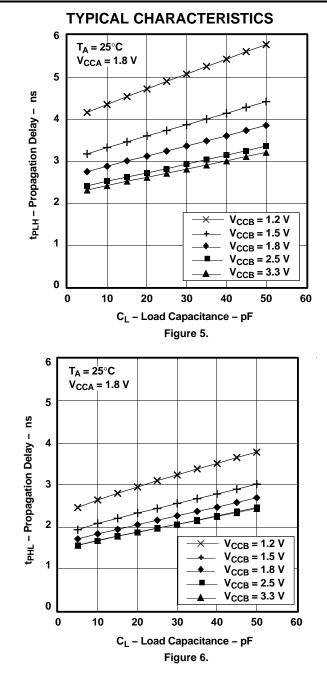
TEXAS INSTRUMENTS

www.ti.com

Figure 4.

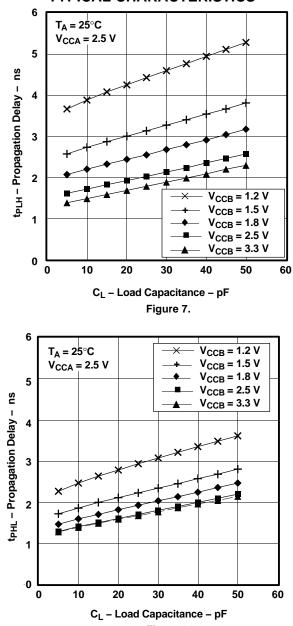


SCES551C-FEBRUARY 2004-REVISED AUGUST 2005



12

SCES551C-FEBRUARY 2004-REVISED AUGUST 2005



TYPICAL CHARACTERISTICS

Ü

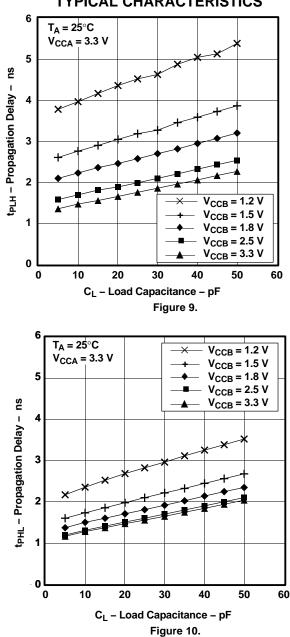
TEXAS INSTRUMENTS

www.ti.com

Figure 8.

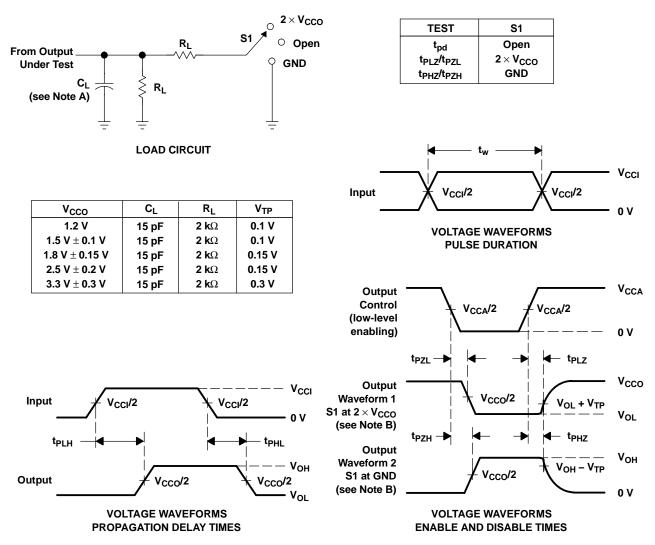


SCES551C-FEBRUARY 2004-REVISED AUGUST 2005



TYPICAL CHARACTERISTICS

SCES551C-FEBRUARY 2004-REVISED AUGUST 2005



PARAMETER MEASUREMENT INFORMATION

NOTES: A. C_L includes probe and jig capacitance.

Texas

TRUMENTS www.ti.com

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_Q = 50 Ω, dv/dt ≥ 1 V/ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .
- H. V_{CCI} is the V_{CC} associated with the input port.
- I. V_{CCO} is the V_{CC} associated with the output port.

Figure 11. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74AVC16T245DGGRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AVC16T245DGGRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AVC16T245DGVRE4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AVC16T245DGVRG4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AVC16T245DGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AVC16T245DGVR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AVC16T245GQLR	NRND	BGA MI CROSTA R JUNI OR	GQL	56	1000	TBD	SNPB	Level-1-240C-UNLIM
SN74AVC16T245ZQLR	ACTIVE	BGA MI CROSTA R JUNI OR	ZQL	56	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

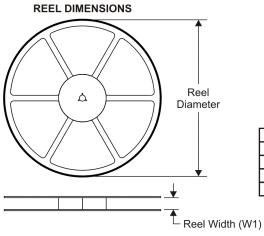
⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

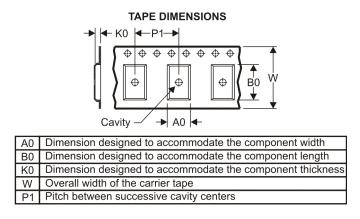
Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

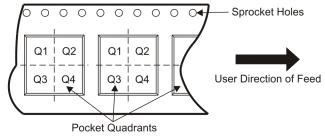
TEXAS INSTRUMENTS www.ti.com

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

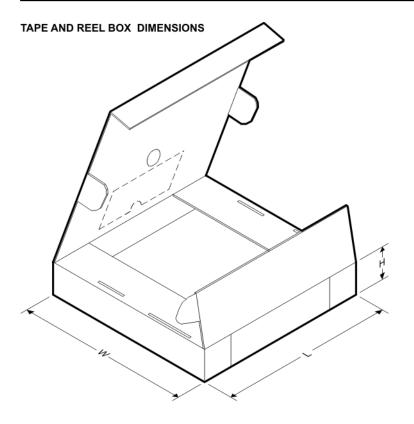


Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AVC16T245DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1
SN74AVC16T245DGVR	TVSOP	DGV	48	2000	330.0	24.4	6.8	10.1	1.6	12.0	24.0	Q1
SN74AVC16T245GQLR	BGA MI CROSTA R JUNI OR	GQL	56	1000	330.0	16.4	4.8	7.3	1.5	8.0	16.0	Q1
SN74AVC16T245GQLR	BGA MI CROSTA R JUNI OR	GQL	56	1000	330.0	16.4	4.8	7.3	1.45	8.0	16.0	Q1
SN74AVC16T245ZQLR	BGA MI CROSTA R JUNI OR	ZQL	56	1000	330.0	16.4	4.8	7.3	1.45	8.0	16.0	Q1
SN74AVC16T245ZQLR	BGA MI CROSTA R JUNI OR	ZQL	56	1000	330.0	16.4	4.8	7.3	1.5	8.0	16.0	Q1



PACKAGE MATERIALS INFORMATION

19-Mar-2008

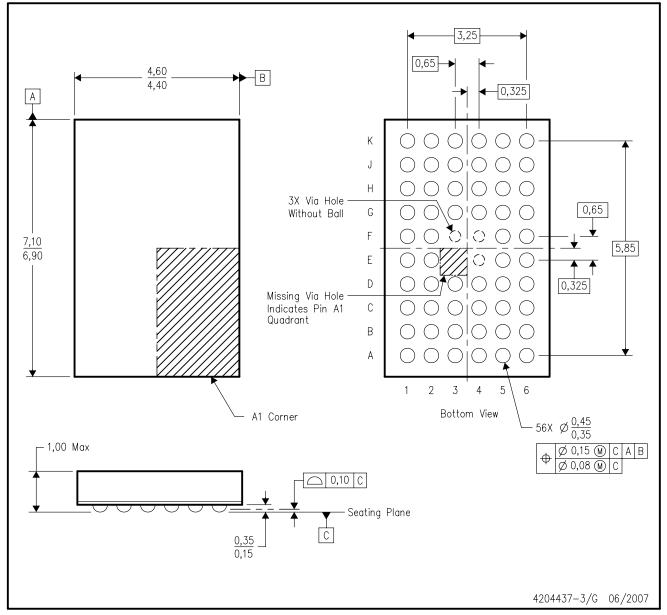


*All dimensions	are nominal
-----------------	-------------

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AVC16T245DGGR	TSSOP	DGG	48	2000	346.0	346.0	41.0
SN74AVC16T245DGVR	TVSOP	DGV	48	2000	346.0	346.0	41.0
SN74AVC16T245GQLR	BGA MICROSTAR JUNIOR	GQL	56	1000	333.2	345.9	28.6
SN74AVC16T245GQLR	BGA MICROSTAR JUNIOR	GQL	56	1000	346.0	346.0	33.0
SN74AVC16T245ZQLR	BGA MICROSTAR JUNIOR	ZQL	56	1000	346.0	346.0	33.0
SN74AVC16T245ZQLR	BGA MICROSTAR JUNIOR	ZQL	56	1000	333.2	345.9	28.6

ZQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-285 variation BA-2.
- D. This package is lead-free. Refer to the 56 GQL package (drawing 4200583) for tin-lead (SnPb).



GQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-285 variation BA-2.
- D. This package is tin-lead (SnPb). Refer to the 56 ZQL package (drawing 4204437) for lead-free.



MECHANICAL DATA

MTSS003D - JANUARY 1995 - REVISED JANUARY 1998

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Clocks and Timers	www.ti.com/clocks	Digital Control	www.ti.com/digitalcontrol
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
RFID	www.ti-rfid.com	Telephony	www.ti.com/telephony
RF/IF and ZigBee® Solutions	www.ti.com/lprf	Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2008, Texas Instruments Incorporated